



[10191/955]

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: Joerg SCHAEFER et al.
SERIAL NO.: 09/238,262
FILED: January 27, 1999
TITLE: METHOD OF PRODUCING STRUCTURED WAFERS
ART UNIT: 1746
EXAMINER: Anita K. Alanko

Assistant Commissioner
for Patents
Washington, D.C. 20231

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PRELIMINARY AMENDMENT UNDER 37 C.F.R. § 1.114

Sir:

In response to the Final Office Action dated August 14, 2001, please reconsider the above identified application based on at least the following:

IN THE CLAIMS:

Please add new Claims 10 - 13 as follows:

-- 10. (New) A method of producing a micromechanical sensor arrangement, comprising the steps of:

providing a single material wafer having a surface and edge areas;
dividing the surface of the wafer into positive areas, to be subsequently etched in a wet chemical etching process, and negative areas including the edge areas of the wafer;
providing the negative areas with a passivation layer to protect the negative areas from the subsequent wet chemical etching process;
etching the wafer in the wet chemical etching process; and
removing the passivation layer.